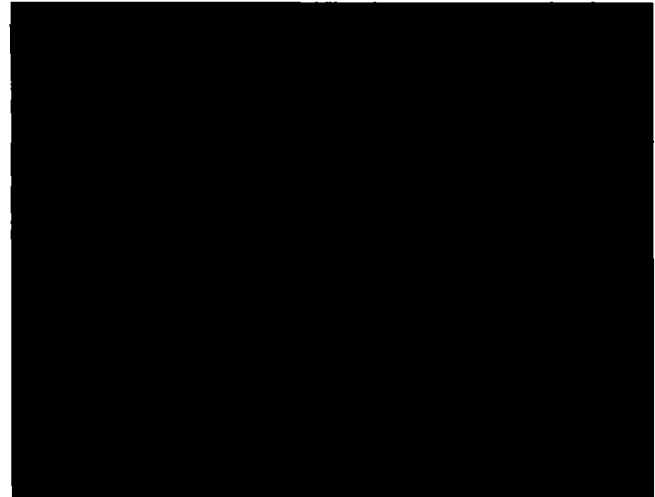


SIMM Sockets — (DIPLOMATE)

Product Facts

- Various circuit sizes available
- Low overall and mated height profiles
- Redundant contact system
- High normal force interface
- Contact anti-overstress design
- Closed bottom design
- Standoffs for flux removal
- Accepts .050±.003 [1.27±0.08] module thicknesses
- Heat resistant housing material
- Simple insertion/extraction of board

- Designed for robotic assembly methods
- Gold plating option
- Provides high density packaging
- Allows for module upgrading
- Low applied cost
- Recognized under the Component Program of Underwriters Laboratories Inc., File No. E28476
- Certified by Canadian Standards Association, File No. LR 7189



Standard Vertical

Memory Module
Extraction Tool
Part No. 382264-1

Note: 30 Pos. Housing Dim. (Typ.)—Single Row, 3.800 [96.52] L x .270 [6.86] W x .510 [12.95] H;
Dual Row, 3.800 [96.52] L x .570 [14.48] W x .510 [12.95] H

No. of Pos. ¹	Single Row Loose Piece		Dual Row .300 [7.62] CL	
	Tin ²	Gold ³	Tin ²	Gold ³
22	643922-1	643922-2	—	—
30	643930-1	643930-2	2-382230-1*	2-382230-2*
35	643935-1	—	—	—
42	643942-1	—	—	—

¹ Other sizes and variations can be made available upon request.

² Bright tin-lead plate

³ .000030 [0.00076] thick gold plate on the contact area and tin-lead plate on the solder tails.

* Packaged in slide tube for robotic assembly.

Low Profile 27° (Angled) Sockets mount on .400 [10.16]* (single row versions) or .500 [12.70] (dual row versions) row-to-row centers

Memory Module
Extraction Tool
Part No. 382264-1

Note: 30 Pos. Housing Dim. (Typ.)—Single Row, 3.800 [96.52] L x .545 [13.84] W x .306 [7.77] H;
Dual Row, 3.800 [96.52] L x .963 [24.46] W x .306 [7.77] H

No. of Pos. ¹	Single Row		Dual Row	
	Tin ²	Gold ³	Tin ²	Gold ³
30	2-382030-1	2-382030-2	2-382130-1	2-382130-2
35	382035-1	—	—	—
42	382042-1	382042-2	—	—

¹ Other sizes and variations can be made available upon request.

² Bright tin-lead plate.

³ .000030 [0.00076] thick gold plate on the contact area and tin-lead plate on the solder tails.

*When mounted on .400 [10.16] centerlines, all modules in front of the one to be removed must be removed first.